PUA3210 (PU3210)

Silicon PNP epitaxial planar type

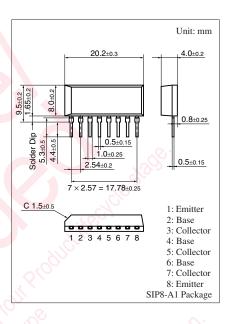
For power amplification
Complementary to PUA3110 (PU3110)

■ Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Large collector current I_C
- PNP 3 elements

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-60	V	
Collector-emitter voltage (Base open)	V_{CEO}	-60	V	
Emitter-base voltage (Collector open)	V_{EBO}	-6	V	
Collector current	I_{C}	-3	A	
Peak collector current	I_{CP}	-5	A	
Base current	I_{B}	-1	A	
Collector power dissipation	P _C	15	W	
$T_a = 25$ °C		2.4		
Junction temperature	T_{j}	150	°CO	
Storage temperature	T_{stg}	-55 to +150	°C	

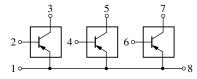


■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

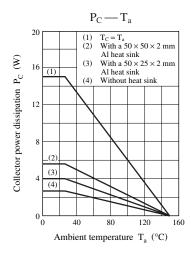
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = -30 \text{ mA}, I_B = 0$	-60	Ull		V
Base-emitter saturation voltage	V_{BE}	$V_{CE} = -4 \text{ V}, I_{C} = -3 \text{ A}$		5	-1.8	V
Collector-emitter cutoff current ($V_{BE} = 0$)	I _{CES}	$V_{CE} = -60 \text{ V}, V_{BE} = 0$	201		-200	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -30 \text{ V}, I_B = 0$	7.7		-300	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -6 \text{ V}, I_C = 0$	7		-1	mA
Forward current transfer ratio	h _{FE1}	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$	70		250	_
	h _{FE2}	$V_{CE} = -4 \text{ V}, I_{C} = -3 \text{ A}$	10			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -3 \text{ A}, I_B = -0.375 \text{ A}$			-1.2	V
Transition frequency	f_T	$V_{CE} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t _{on}	$I_C = -1 A$		0.5		μs
Storage time	t _{stg}	$I_{B1} = -0.1 \text{ A}, I_{B2} = 0.1 \text{ A}$		1.2		μs
Fall time	t _f	$V_{CC} = -50 \text{ V}$		0.3		μs

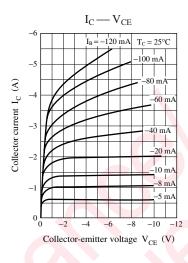
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

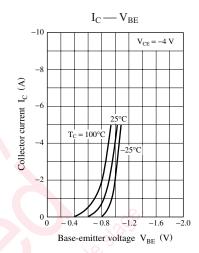
■ Internal Connection

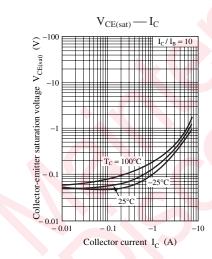


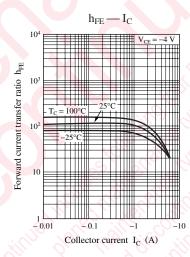
Note) The part number in the parenthesis shows conventional part number.

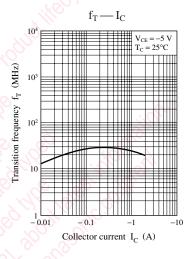


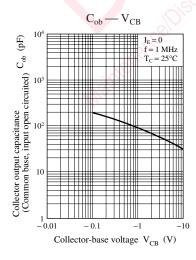


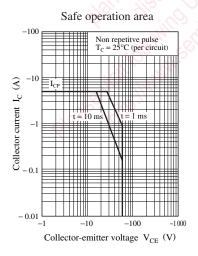












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